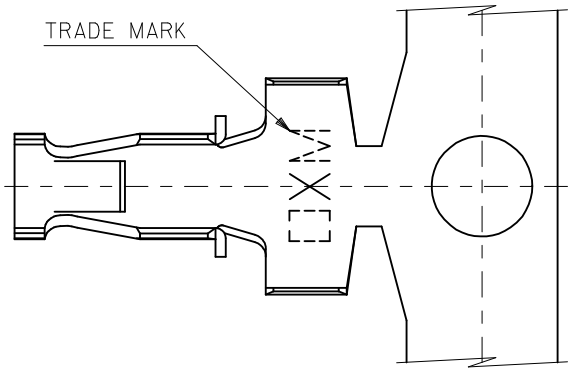
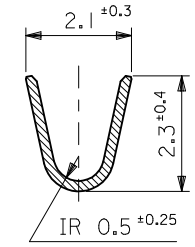
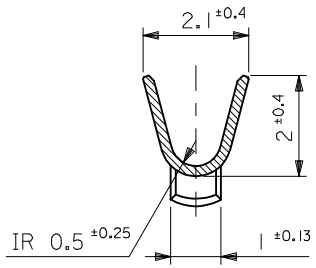
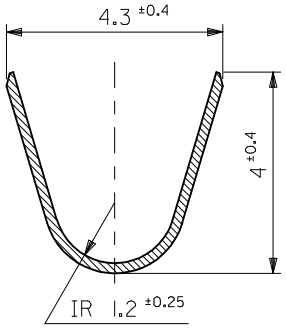




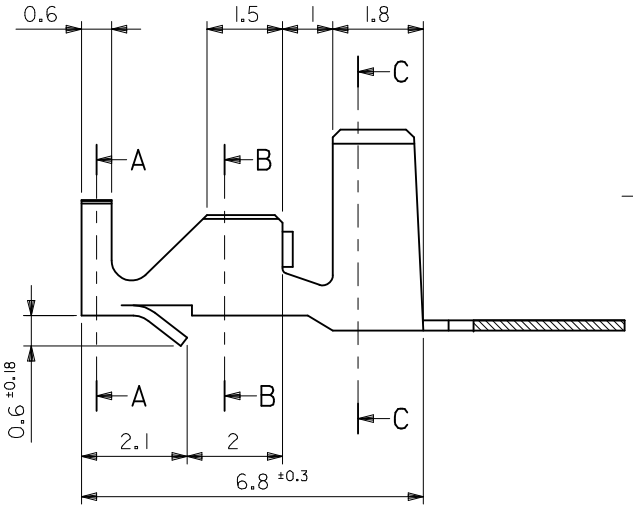
SECT. A-A

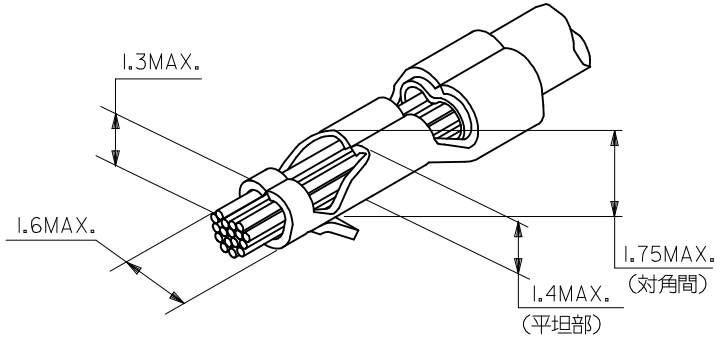


SECT. B-B



SECT. C-C





圧着外観図
OUTSIDE VIEW OF CRIMP

NOTES

1. 推奨プリント基板穴径：Φ1.8 +0.1 0
   RECOMMENDED P.C.B. HOLES : Ø1.8 +0.1 0
2. 推奨プリント基板厚：t1.57 ±0.2
   RECOMMENDED P.C.B. THICKNESS : 1.57 ±0.2
3. 材料の厚み：0.203
   MATERIAL THICKNESS : 0.203

PLATING	MATERIAL	FORM	EDP NO.	ENG. NO.
TIN-LEAD(90-10) 3.8 µm MIN. OVER NICKEL 1.3 µm MIN.	PHOSPHOR BRONZE	CHAIN	39-00-0277	5298PBPT
TIN 0.9 µm MIN. REFLOW TREATMENT (PRE-PLATED)	PHOSPHOR BRONZE	CHAIN	39-00-0230	5298PBT
TIN 0.9 µm MIN. OVER COPPER 0.5 µm MIN. (PRE-PLATED)	BRASS	CHAIN	08-70-0106	5298T

材料 MATERIAL	SEE TABLE & NOTE
仕上げ FINISH	— // —
適用電線範囲 WIRE RANGE	AWG #18-22
被覆外径 INS. RANGE	Φ1.7-3.05

REVISED
EC NO: J2017-0224 2016/10/12
DRWN:MNISHIKAWA 2016/10/12
CH'KD:KTAKAHASHI 2016/10/14
APPR:MSASAO

REV	DESCRIPTION
—	

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER		±
0.25	OVER	0.5 UNDER	±
0.5	OVER	1.0 UNDER	±
0	OVER	10 UNDER	±0.2
10	OVER	30 UNDER	±0.25
30	OVER		±0.3
ANGULAR		±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: H.HIRAMOTO DATE: '91/09/05
CHECKED BY: H.HIRAMOTO DATE: '93/07/06
APPROVED BY: M.FUKUSHIMA DATE: '93/07/06

TITLE
LOW PROFILE PC BOARD CRIMP PIN

molex

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-5298-001
SHEET NO.: 1 OF 1
SIZE: A3

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